BRCS500P10ZC

Rev.A Sep.-2023

DATA SHEET

/ Descriptions

PDFN5 6 MOS

P-CHANNEL MOSFET in a PDFN5 6 Plastic Package.

/ Features

V_{DS}(V)=-100V I_D=-29A

$R_{DS(ON)}$@-10V<50mΩ(Typ.42mR)

$R_{DS(ON)}$@-4.5V<55mΩ(Typ.45mR)

HF Product.

/ Applications

Power Management of Industrial DC/DC Converter.

PIN1 2 3 S PIN 4 G PIN 5 6 7 8 D

/ Marking

See Marking Instructions.

@ ƒ Parameter	… Z Symbol	y ¡ Ú ^ Test Conditions	Â 4 › Min	Á º › Typ	Â Ý › Max	% y Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=-10V V_{DS}=-50V R_L=10 ¡ R_{GEN}=3 ¡		6		ns
Turn-On Rise Time	t_r			2.4		
Turn-Off Delay Time	$t_{d(off)}$			19		

Ô ? d • Ž ¢ / Electrical Characteristic Curve

Ô ? d • Ž ¢ / Electrical Characteristic Curve

Ø ¤ =) ¢ / Package Dimensions

, M y ƒ / Marking Instructions

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500P10
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500P10 y	D } º Z
y	ÿ D Z W A k š ÿ D Z J

Note y

BR y	Company Code
500P10 y	Product Type Code
****:	Lot No. Code, code change with Lot No

š WD t … • Ž ¢ (x /) / Temperature Profile for IR Reflow Soldering(Pb-Free)

ª ¢ y
1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;
2o• Q › “ † 245 r5 - k ž • 4 Ò 5 r0.5sec;
3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:
1.Preheating:150~180 - , Time:60~90sec.
2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.
3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r5 - ž • y 10 r1 sec.

Temp.:260±5 Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL